LEADER TIME SRL

PRODUCT SPECIFICATION

16*4 Characters COB LCD MODULE
MODEL: LT-1604A-801 Ver:1.0

< ◇ > Finally Specification

CUSTOMER'S APPROVAL	
CUSTOMER :	
SIGNATURE:	DATE:

APPROVED BY	PM REVIEWD	PD REVIEWD	PREPARED By

Prepared By:

LEADER TIME SRL

VIA MONS. PROSDOCIMI, 27

36042 BREGANZE (VI)

- This specification is subject to change without notice. Please contact LT or it's representative before designing your product based on this specification.

Revision Status

Version	Revise Date	Page	Content	Modified By
Ver 1.0	**2014.11.19**		**First Issued**	

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No. Contents Page

1. Features

The features of LCD are showed as follows

* Display mode : STN/Blue/Transmissive/Negative/anti-UV
* Controller IC : AIP31066(English and Japanese)
* Display format : 16X4Characters
* Interface : 4 Bit or 8 Bit MPU
* Driving Method : 1/16Duty, 1/5Bias
* Viewing Direction : 12 O'clock
* Backlight : 3 LED /White
*Sample NO. : C1604A9SGW7B-B0_01/20141114

2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	87(W) x60(H) x14.5MAX(D)	mm
Viewing Area	61.8 (W) x 25.2(H)	mm
Activity Display Area	56.21(W)x20.81(H)	mm
Character Font	5x8 Dots	-
Character Size	2.96(W)x4.76(H)	mm
Character Pitch	3.55 (W) x5.35(H)	mm
Dot Size	0.56(W)x0.56(H)	mm

3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C)

Item	Symbol	Min	Max	Unit
Supply Voltage For Logic	V_{DD}	-0.3	7.0	V
Supply Voltage For LCD Drive	V_{LCD}	V_{DD}-10	V_{DD}+0.3	V
Input Voltage	Vin	-0.3	V_{DD}+0.3	V
Operating Temp.	Top	-20	+70	°C
Storage Temp.	Tst	-30	+80	°C

*****. NOTE: The response time will be extremely slow when the operating temperature is around -10℃, and the back ground will become darker at high temperature operating.

3-2 ELECTRICAL CHARACTERISTICS

Item		Symbol	Test Condition	Min.	Typ.	Max.	Unit
Logic supply Voltage		V_{DD} – Vss	Ta = 25 °C VDD=5V ± 5%	-	5	-	V
LCD Drive		V_{OP}=V_{DD} –V5		4.0	4.2	4.4	V
Input Voltage	"H" Level (Except OSC1)	V_{IH1}		0.7V_{DD}	-	V_{DD}	V
	"L" Level (Except OSC1)	V_{IL1}		-0.3	-	0.55	V
	"H" Level (OSC1)	V_{IH2}		0.7V_{DD}	-	V_{DD}	V
	"L" Level (OSC1)	V_{IL2}		-0.2	-	0.2V_{DD}	V
Frame Frequency		f_{FLM}		-	75	-	Hz
Current Consumption		I_{DD}		-	1.5	-	mA

3-3BACKLIGHT

3-3-1. Absolute Maximum Ratings

Item	Symbol	Condition	min	Typ	Max	Unit
Forward Current	IF	Ta = 25 °C	-	-	60	mA
Power Dissipation	PD		-	-	200	mW
ReverseCurrent	IR	VR=5.0V/LED	-	-	15	uA

3-3-2. Electrical-optical Characteristics

Item	Symbol	Condition	min		Typ		Max		Unit
Forward Voltage	VF	IF=45mA Ta = 25 °C	2.9		3.1		3.3		V
Average Luminous Intensity	Iv		150		-		-		cd/m^2
Colourcoordonate	-		X	Y	X	Y	X	Y	-
			0.25	0.25	0.28	0.28	0.31	0.31	

The brightness is measured without LCD panel

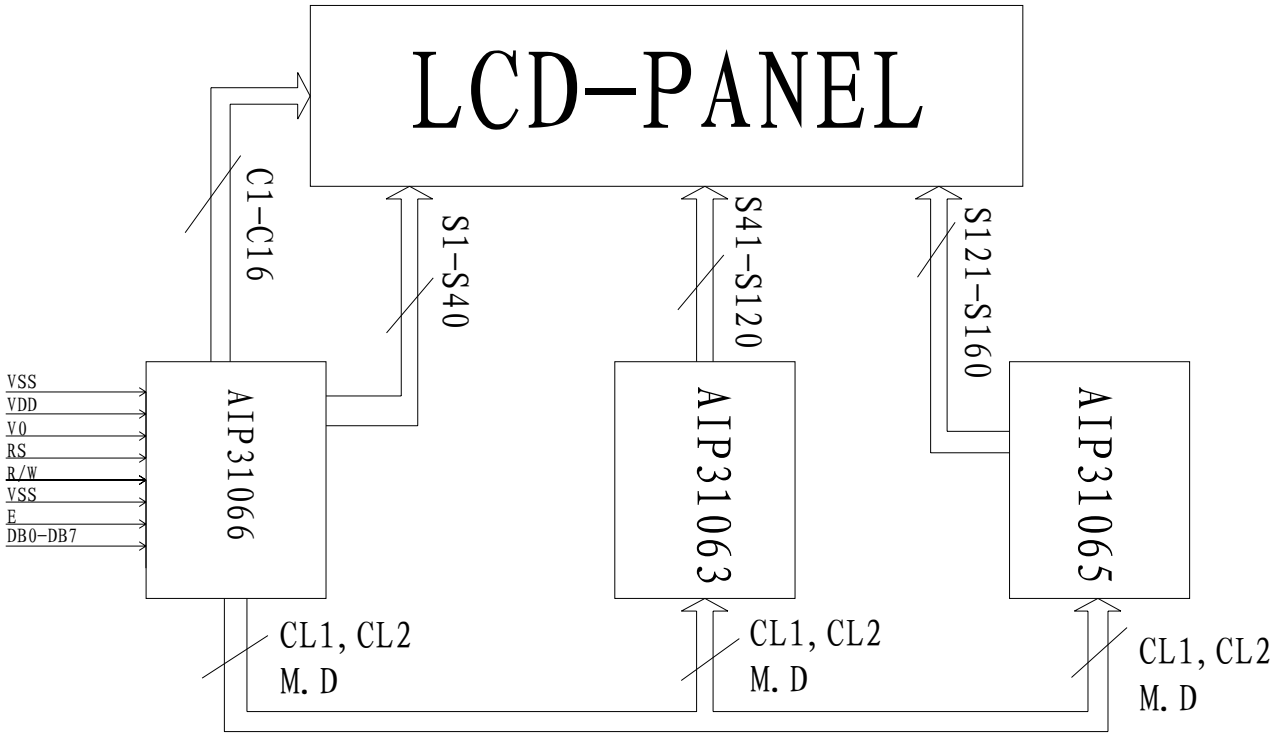
For operation above 25 °C,Thelfm&Pd must be derated , the current derating is -0.36mA/°C for DC drive and -0.86mA/°C for Pulse drive ,the Power dissipation is -0.75mW/°C.The product working current must not more than the 60% of the lfm or Ifp according to the working temperature.

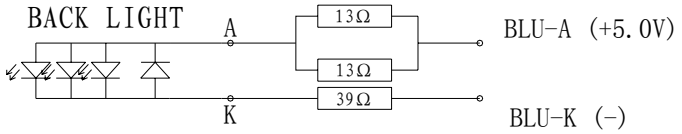
4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

4-1 INTERFACE PIN FUNCTION DESCRIPTION

PIN NO.	SYMBOL	FUNCTIONS
1	VSS	Ground
2	VDD	Supply voltage for logical circuit
3	V0	Supply voltage for LCD driving
4	RS	A signal for selecting registers.
5	R/W	A signal for selecting read or write actions.1: Read, 0: Write.
6	E	Read / Write enable signal
7-14	DB0~DB7	Data Bus
15	BLU-A	Backlight (5.0V)
16	BLU-K	Backlight (-)

4-2 BLOCK DIAGRAM



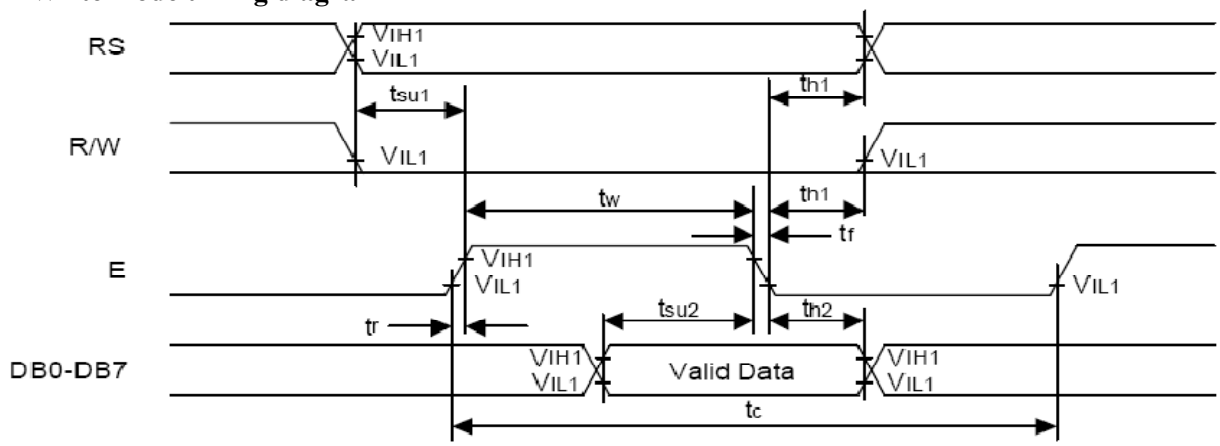


5. TIMING CHARACTERISTICS

5 - 1 Write mode

Mode	Characteristics	Symbol	Min	Typ	Max	Unit
Write Mode	E Cycle Time	tc	500	–	–	ns
(refer to Figure-6)	E Rise/Fall Time	t_R, t_F	–	–	20	
	E Pulse Width (High, Low)	tw	230	–	–	
	R/W and RS Setup Time	tsu1	40	–	–	
	R/W and RS Hold Time	t_{H1}	10	–	–	
	Data Setup Time	tsu2	80	–	–	
	Data Hold Time	t_{H2}	10	–	–	

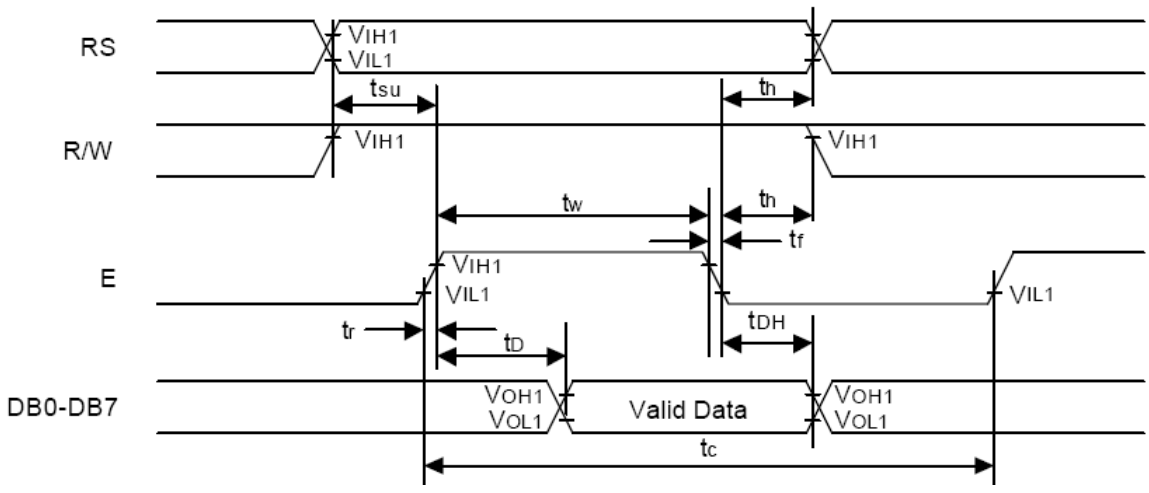
5-2 Write mode timing diagram



5.3 Read mode

Read Mode	E Cycle Time	tc	500	–	–	ns
(refer to Figure-7)	E Rise/Fall Time	t_R, t_F	–	–	20	
	E Pulse Width (High, Low)	tw	230	–	–	
	R/W and RS Setup Time	tsu	40	–	–	
	R/W and RS Hold Time	t_H	10	–	–	
	Data Output Delay Time	tD	–	–	120	
	Data Hold Time	tDH	5	–	–	

5-4Read mode timimg diagram



6. COMMAND LIST

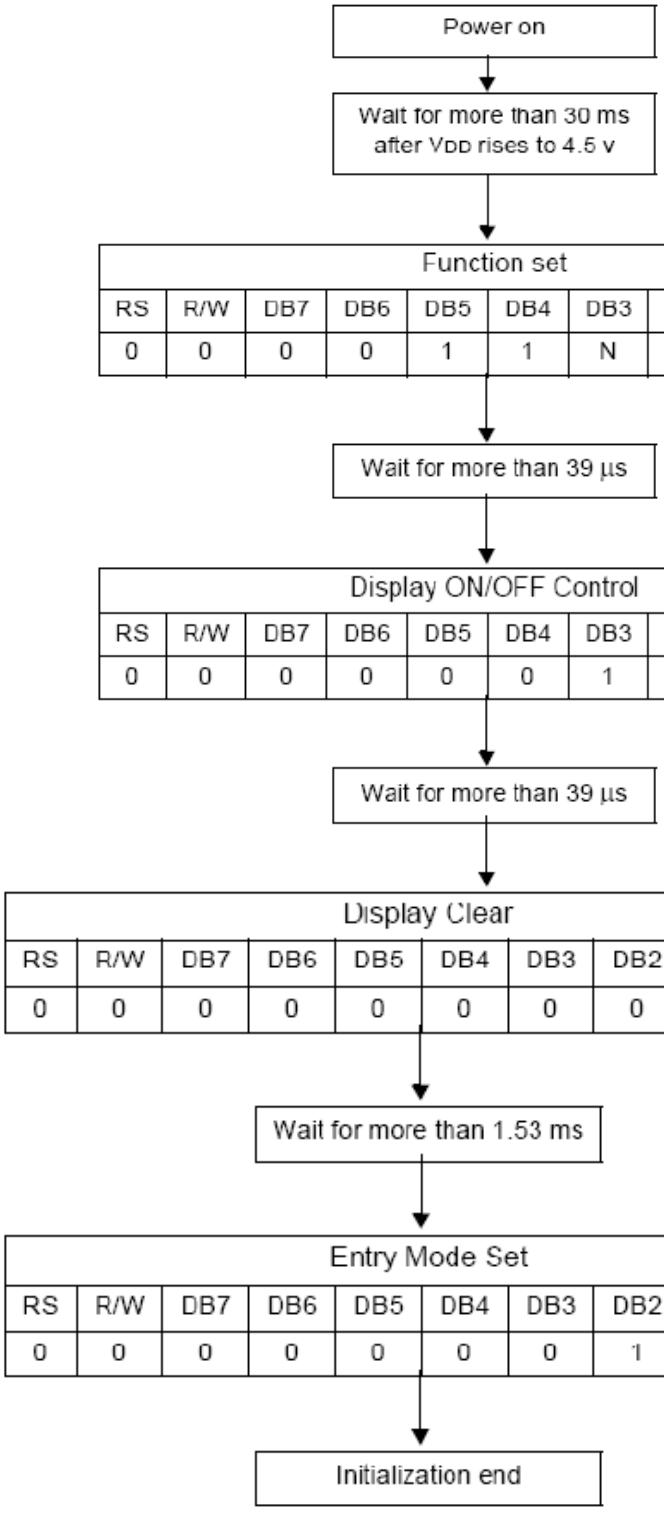
6-1 Instruction Table

Instruction	Instruction Code										Description	Execution
	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Instruction Code	time(fsoc=270)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from AC.	1.53ms
Return Home	0	0	0	0	0	0	0	0	1	X	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.53ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	SH	Assign cursor moving direction and make shift of entire display enable.	39μs
Display ON/OFF Control	0	0	0	0	0	0	1	D	C	B	Set display(D), cursor(C), and blinking of cursor(B) on/off control bit.	39μs
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	X	X	Set cursor moving and display shift control bit, and the direction, without changing DDRAM data.	39μs
Function Set	0	0	0	0	1	DL	N	F	X	X	Set interface data length (DL : 4-bit/8-bit), numbers of display line (N : 1-line/2-line), display font type (F : 5 X 8 dots/ 5 X 11 dots)	39μs
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter.	39μs
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter.	39μs
Read Busy Flag and Address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0μs
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	43μs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	43μs

NOTE: When an MPU program with checking the Busy Flag (DB7) is made, it must be necessary 1/2 fosc is necessary for executing the next instruction by the falling edge of the 'E' signal after the Busy Flag (DB7) goes to "LOW".

INITIALIZING BY INSTRUCTION

1) 8-bit interface mode (Condition: fosc = 270KHZ)



N	0	1-line mode
	1	2-line mode

F	0	display off
	1	display on

D	0	display off
	1	display on

C	0	cursor off
	1	cursor on

B	0	blink off
	1	blink on

I/D	0	decrement mode
	1	increment mode

SH	0	entire shift off
	1	entire shift on

7. CHARACTER GENERATOR ROM

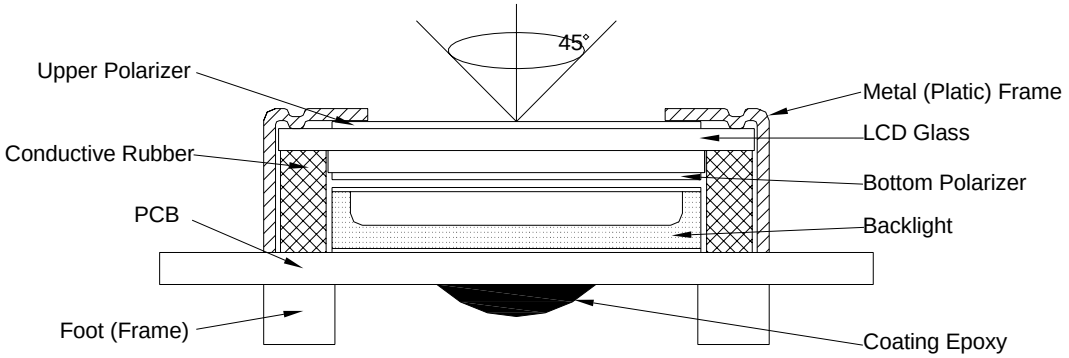
Lower 4 Bits \ Upper 4 Bits	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
xxxx0000	CG RAM (1)			0	@	P	`	p				ー	タ	ミ	α	p
xxxx0001	(2)		!	1	A	Q	a	q			。	ア	チ	ム	ä	q
xxxx0010	(3)		"	2	B	R	b	r			「	イ	ツ	メ	ß	θ
xxxx0011	(4)		#	3	C	S	c	s			」	ウ	テ	モ	ε	∞
xxxx0100	(5)		$	4	D	T	d	t			、	エ	ト	ヤ	μ	Ω
xxxx0101	(6)		%	5	E	U	e	u			・	オ	ナ	ユ	σ	ü
xxxx0110	(7)		&	6	F	V	f	v			ヲ	カ	ニ	ヨ	ρ	Σ
xxxx0111	(8)		'	7	G	W	g	w			ァ	キ	ヌ	ラ	g	π
xxxx1000	(1)		(	8	H	X	h	x			ィ	ク	ネ	リ	√	x̄
xxxx1001	(2)		)	9	I	Y	i	y			ゥ	ケ	ノ	ル	⁻¹	y
xxxx1010	(3)		*	:	J	Z	j	z			ェ	コ	ハ	レ	j	千
xxxx1011	(4)		+	;	K	[	k	{			ォ	サ	ヒ	ロ	ˣ	万
xxxx1100	(5)		,	<	L	¥	l	|			ャ	シ	フ	ワ	¢	円
xxxx1101	(6)		−	=	M	]	m	}			ュ	ス	ヘ	ン	£	÷
xxxx1110	(7)		.	>	N	^	n	→			ョ	セ	ホ	゛	ñ	
xxxx1111	(8)		/	?	O	_	o	←			ッ	ソ	マ	°	ö	■

Note: The user can specify any pattern for character-generator RAM.

8. QUALITY SPECIFICATIONS

8-1. LCM Appearance and Electric inspection Condition

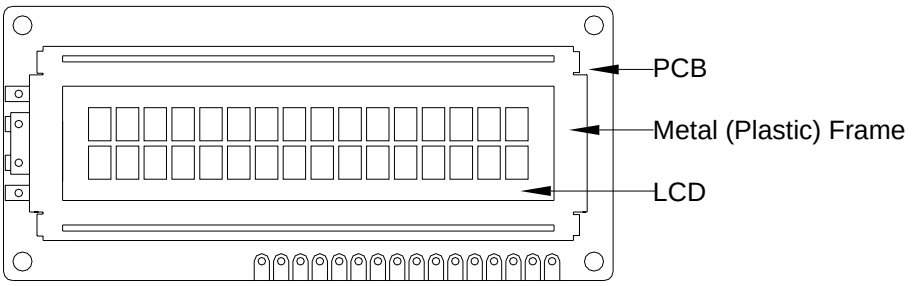
1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



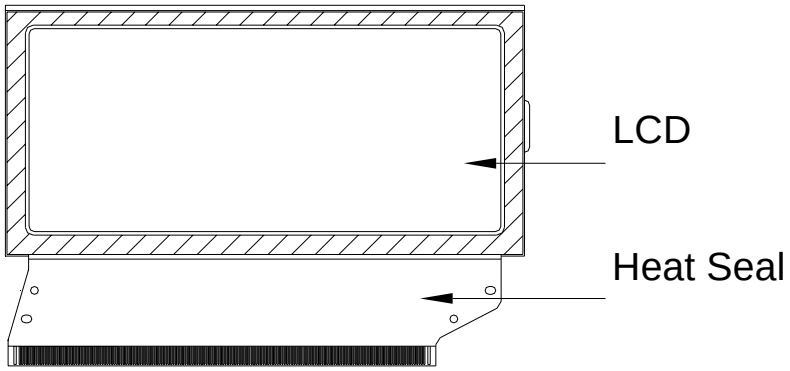
2. View Angle: with in 45˚around perpendicular line.

8-2. Definition

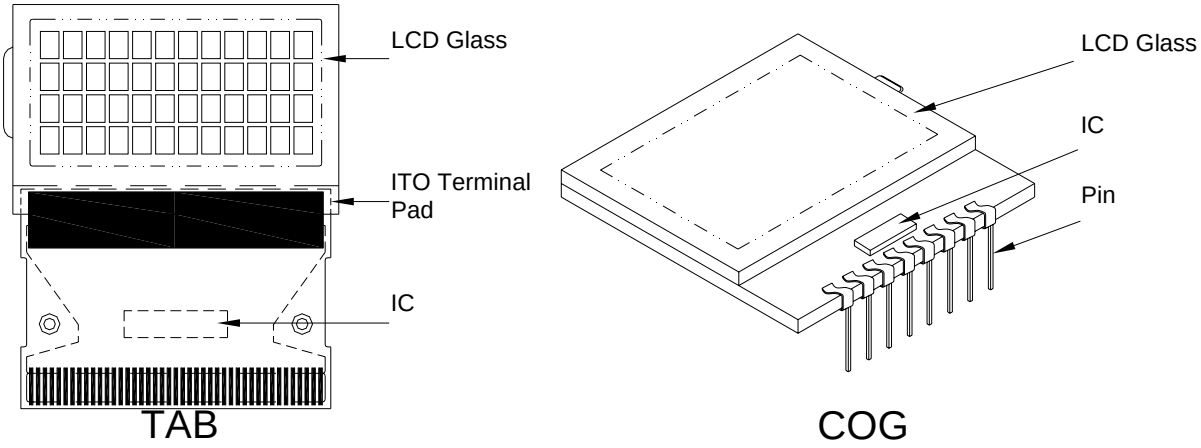
1. COB



2. Heat Seal



3. TAB and COG



8-3. Sampling Plan and Acceptance

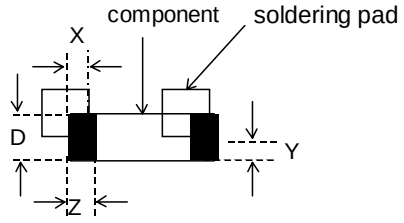
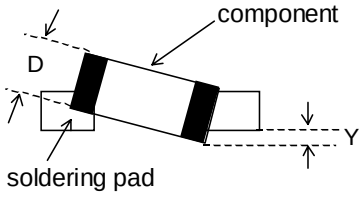
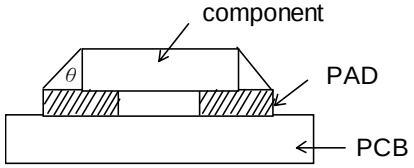
1. Sampling Plan
   MIL - STD - 105E (||) ordinary single inspection is used.
2. Acceptance
   Major defect: AQL = 0.65%
   Minor defect: AQL = 1.5%

8-4. Criteria

1. COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm^2	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

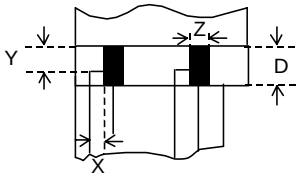
2. SMT

Defect	Inspection Item	Inspection Standards	
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing , extra, wrong component or wrong orientation		Reject
Minor	Component position shift 	X < 3/4Z Y > 1/3D	Reject Reject
Minor	Component tilt 	Y > 1/3D	Reject
Minor	Insufficient solder 	$\theta \leq 20^\circ$	Reject

3. Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards		
Major	Crack / breakage	Anywhere		Reject
Minor	Frame Scratch	W	L	Acceptable of Scratch
		w<0.1mm	Any	Ignore
		0.1≤w<0.2mm	L≤5.0mm	2
		0.2≤w<0.3mm	L≤3.0mm	1
		w≥0.3mm	Any	0
		Note : 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (not visible) can be ignored .		
Minor	Frame Dent , Prick $\Phi = \frac{L+W}{2}$			Acceptable of Dents / Pricks
		$\Phi \leq 1.0$mm		2
		$1.0 < \Phi \leq 1.5$mm		1
		$1.5\text{mm} < \Phi$		0
		Note : 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (not visible) can be ignored		
Minor	Frame Deformation	Exceed the dimension of drawing		
Minor	Metal Frame Oxidation	Any rust		

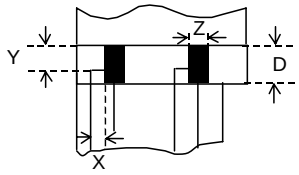
4. Flexible Film Connector (FFC)

Defect	Inspection Item		Inspection Standards	
Minor	Tilted soldering		Within the angle +5°	Acceptable
Minor	Uneven solder joint /bump			Reject
Minor	Hole	$\Phi = \frac{L+W}{2}$	Expose the conductive line	Reject
			$\Phi > 1.0$mm	Reject
Minor	Position shift 		Y > 1/3D	Reject
			X > 1/2Z	Reject

5. Screw

Defect	Inspection Item	Inspection Standards	
Major	Screw missing/loosen		Reject
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reject

6. Heatseal、TCP 、FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L+W}{2}$	Φ> 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift 	Y > 1/3D	Reject
		X > 1/2Z	Reject
Major	Conductive line break		Reject

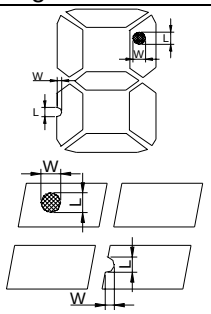
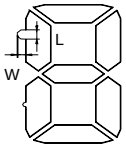
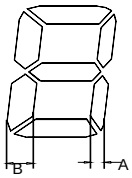
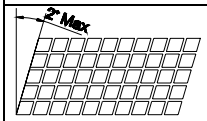
7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards	
Minor	LED dirty, prick	Acceptable number of units	
		$\Phi \leq$0.10mm	Ignore
		0.10< $\Phi \leq$0.15mm	2
		0.15< $\Phi \leq$0.2mm	1
		Φ>0.2mm	0
		The distance between any two spots should be $\geq$5mm Any spot/dot/void outside of viewing area is acceptable	
Minor	Protective film tilt	Not fully cover LCD	Reject
Major	COG coating	Not fully cover ITO circuit	Reject

8. Electric Inspection

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

9. Inspection Specification of LCD

Defect	Inspect Item		Inspection Standards				
Minor	Linear Defect	∗Glass Scratch ∗Polarizer Scratch ∗ Fiber and Linear material	W	W≤0.03		0.03<W≤0.05	W>0.05
			L	L<5		L<3	Any
			ACC. NO.	1		1	Reject
			Note	L is the length and W is the width of the defect			
Minor	Black Spot and Polarizer Pricked	∗ Foreign material between glass and polarizer or glass and glass ∗ Polarizer hole or protuberance by external force	Φ	Φ≤0.1	0.1<Φ≤0.15	0.15<Φ≤0.2	Φ>0.2
			ACC. NO.	3EA / 100mm^2	2	1	0
			Note	Φ is the average diameter of the defect. Distance between two defects >10mm.			
Minor	White Spot and Bubble in polarizer	∗ Unobvious transparant foreign material between glass and glass or glass and polarizer ∗ Air protuberance between polarizer and glass	Φ	Φ≤0.3		0.3<Φ≤0.5	0.5<Φ
			ACC. NO.	3EA / 100mm^2		1	0
			Note	Φ is the average diameter of the defect. Distance between two defects >10mm.			
Minor	Segment Defect		Φ	Φ≤0.10	0.10<Φ≤0.20	0.20<Φ≤0.25	Φ>0.25
			ACC. NO.	3EA / 100mm^2	2	1	0
			Note	W is more than 1/2 segment width			Reject
				$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm			
Minor	Protuberant Segment	 Φ = (L + W) / 2	Φ	Φ≤0.10	0.10<Φ≤0.20	0.20<Φ≤0.25	Φ>0.25
			W	Glue	W≤1/2 Seg W≤0.2	W≤1/2 Seg W≤0.2	Ignore
			ACC. NO.	3EA / 100mm^2	2	1	0
Minor	Assembly Mis-alignment		1. Segment				
			B	B≤0.4mm	0.4<B≤1.0mm	B>1.0mm	
			B-A	B-A<1/2B	B-A<0.2	B-A<0.25	
			Judge	Acceptable	Acceptable	Acceptable	
			2. Dot Matrix				
			Deformation>2°				Reject
Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the above items: “Black spot” and “White Spot”				

9. RELIABILITY

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity	50℃, 90%RH, 96Hrs	2	GB/T2423.3 -2006
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20℃, 60min~70℃, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	2	GB/T5170.14 -2009
8	Electrical Static Discharge	Air:±8KV 150pF/330Ω 5 times Contact:±4KV 150pF/330Ω 5 times	2	GB/T17626.2 -2006
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8 -1995

Note:1) Above conditions are suitable for our company standard products.
2) For restrict products, the test conditions listed as above must be revised.

10. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily getdamaged since the Module is fixed by utilizing fitting holesin the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichlorotrifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics

(3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. Andground your body, Work/assembly table. Andassembly equipment toprotect against staticelectricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.

(5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them.However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is required.

(6) Storage

In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

(7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol.Which should be burned up later.

When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

(8) Other

- After the product shipped,any product quality issues must be feedback within three months,otherwise,we will not be responsible for the subsequent or consequential events.

11. OUTLINE DIMENSION